

## **DC/DC Converter**

**TEA 1E Series, 1 Watt** 

Highly cost efficient design

• I/O isolation: 1'500 VDC

Operating temperature range
 -40 to +85 °C without derating

• 5 VDC (±10%) input voltage range

Unregulated outputs

• Efficiency up to 78%

• Industry standard SIP-7 package

• 3-year product warranty



The TEA 1E is an unregulated 1 Watt DC/DC SIP-7 converter series which is specifically designed to offer a low-cost solution while keeping a high quality standard. This new series focuses on a simple but effective design approach, which minimizes component and labor cost and is complemented with a complete automatization of the manufacturing process. An operating temperature range from -40°C to 85°C without derating and an I/O-isolation of 1'500 VDC enables this series to cover many different applications. The industry standard package of this converter offers a broad application range in any space, cost critical application and is especially suited for high volume projects where simple but reliable products are needed.

Models				
Order Code	Input Voltage Range	Output Voltage nom.	Output Current max.	Efficiency typ.
TEA 1-0505E	<b>4.5 - 5.5 VDC</b> (5 VDC nom.)	5 VDC	200 mA	78 %

www.tracopower.com September 16, 2022 Page 1 / 3



Input Specifications	
Input Current - At no load	28 mA typ.
Surge Voltage	9 VDC max. (1 s max.)
Recommended Input Fuse	500 mA (slow blow)
	(The need of an external fuse has to be assessed in the final application.)
Input Filter	Internal Capacitor

Voltage Set Accuracy		<b>±3% max.</b> (at 60 % load)
Regulation	- Input Variation (1% Vin step)	1.5% max.
	- Load Variation (10 - 90%)	9% max.
Ripple and Noise	- 20 MHz Bandwidth	50 mVp-p typ.
		100 mVp-p max.
Capacitive Load		1'000 μF max.
Minimum Load		Not required
Temperature Coefficier	nt	±0.03 %/K max.
Start-up Time		30 ms max.
Short Circuit Protection	1	Limited 1 s max., Automatic recovery

## Safety Specifications Safety Standards - IT / Multimedia Equipment Designed for EN 62368-1 (no certification)

Relative Humidity  Temperature Ranges - Operating Temperature - Case Temperature - Storage Temperature - Stora	<b>General Specifica</b>	tions	
Case Temperature	Relative Humidity		95% max. (non condensing)
Storage Temperature	Temperature Ranges	- Operating Temperature	-40°C to +95°C
Power Derating       - High Temperature       5 %/K above 85°C         Cooling System       Natural convection (20 LFM)         Switching Frequency       100 kHz typ. (Royer)         Insulation System       Functional Insulation         Isolation Test Voltage       - Input to Output, 60 s       1'500 VDC         Isolation Resistance       - Input to Output, 500 VDC       1'000 MΩ min.         Isolation Capacitance       - Input to Output, 100 kHz, 1 V       30 pF typ.         Reliability       - Calculated MTBF       2'000'000 h (MIL-HDBK-217F, ground benign)         Washing Process       Not allowed         Housing Material       Plastic (UL 94 V-0 rated)         Potting Material       Phosphor Bronze (C5191)         Pin Foundation Plating       Nickel (1 μm min.)         Pin Surface Plating       Nickel (1 μm min.)         Fin (3 μm min.), bright       Plastic Case         Mounting Type       PCB Mount         Connection Type       THD (Through-Hole Device)         Footprint Type       SIP7         Soldering Profile       Wave Soldering 265 °C / 5 s max.		- Case Temperature	+105°C max.
Cooling System   Natural convection (20 LFM)		- Storage Temperature	-55°C to +125°C
Switching Frequency       100 kHz typ. (Royer)         Insulation System       Functional Insulation         Isolation Test Voltage       - Input to Output, 60 s       1'500 VDC         Isolation Resistance       - Input to Output, 500 VDC       1'000 MΩ min.         Isolation Capacitance       - Input to Output, 100 kHz, 1 V       30 pF typ.         Reliability       - Calculated MTBF       2'000'000 h (MIL-HDBK-217F, ground benign)         Washing Process       Not allowed         Housing Material       Plastic (UL 94 V-0 rated)         Potting Material       Epoxy (UL 94 V-0 rated)         Pin Material       Phosphore Bronze (C5191)         Pin Foundation Plating       Nickel (1 μm min.)         Pin Surface Plating       Tin (3 μm min.), bright         Housing Type       Plastic Case         Mounting Type       PCB Mount         Connection Type       THD (Through-Hole Device)         Footprint Type       SIP7         Soldering Profile       Wave Soldering         265 °C / 5 s max.	Power Derating	- High Temperature	5 %/K above 85°C
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Pin Material       Phosphor Bronze (C5191)         Pin Foundation Plating       Nickel (1 μm min.)         Pin Surface Plating       Tin (3 μm min.), bright         Housing Type       Plastic Case         Mounting Type       PCB Mount         Connection Type       THD (Through-Hole Device)         Footprint Type       SIP7         Soldering Profile       Wave Soldering 265 °C / 5 s max.	Housing Material		Plastic (UL 94 V-0 rated)
Pin Foundation Plating       Nickel (1 μm min.)         Pin Surface Plating       Tin (3 μm min.), bright         Housing Type       Plastic Case         Mounting Type       PCB Mount         Connection Type       THD (Through-Hole Device)         Footprint Type       SIP7         Soldering Profile       Wave Soldering 265 °C / 5 s max.	Potting Material		Epoxy (UL 94 V-0 rated)
Pin Surface Plating  Tin (3 µm min.), bright  Housing Type  Plastic Case  Mounting Type  PCB Mount  Connection Type  THD (Through-Hole Device)  Footprint Type  SIP7  Soldering Profile  Wave Soldering 265 °C / 5 s max.	Pin Material		Phosphor Bronze (C5191)
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Connection TypeTHD (Through-Hole Device)Footprint TypeSIP7Soldering ProfileWave Soldering 265 °C / 5 s max.	Housing Type		Plastic Case
Footprint Type SIP7 Soldering Profile Wave Soldering 265 °C / 5 s max.	Mounting Type		PCB Mount
Soldering Profile  Wave Soldering 265 °C / 5 s max.	Connection Type		THD (Through-Hole Device)
265 °C / 5 s max.	Footprint Type		SIP7
	Soldering Profile		Wave Soldering
Weight 2 g			265 °C / 5 s max.
	Weight		2 g

All specifications valid at nominal voltage, resistive full load and +25°C after warm-up time, unless otherwise stated.



Environmental Compliance - REACH Declaration

- RoHS Declaration

www.tracopower.com/info/reach-declaration.pdf

REACH SVHC list compliant REACH Annex XVII compliant

www.tracopower.com/info/rohs-declaration.pdf

Exemptions: 7a, 7c-I

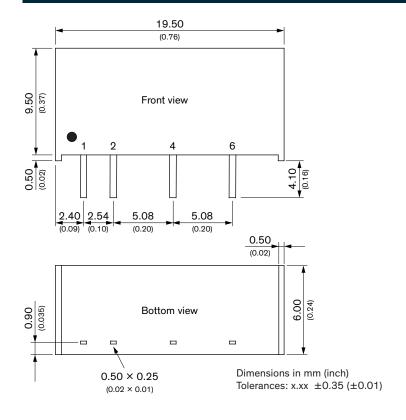
(RoHS exemptions refer to the component concentration only, not to the overall concentration in the product (O5A rule). The SCIP number is provided on request.)

## **Supporting Documents**

Overview Link (for additional Documents)

www.tracopower.com/overview/tea1e

## **Outline Dimensions**



Pinout		
Pin	Pin Function	
1	+Vin (Vcc)	
2	–Vin (GND)	
4	–Vout	
6	+Vout	